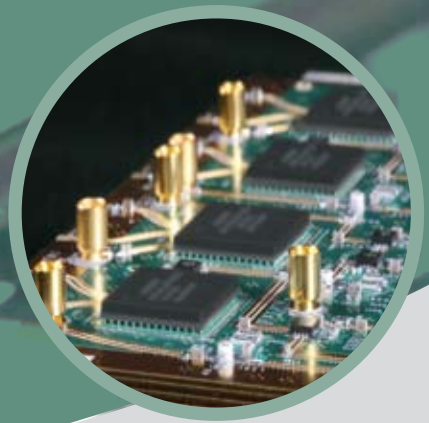
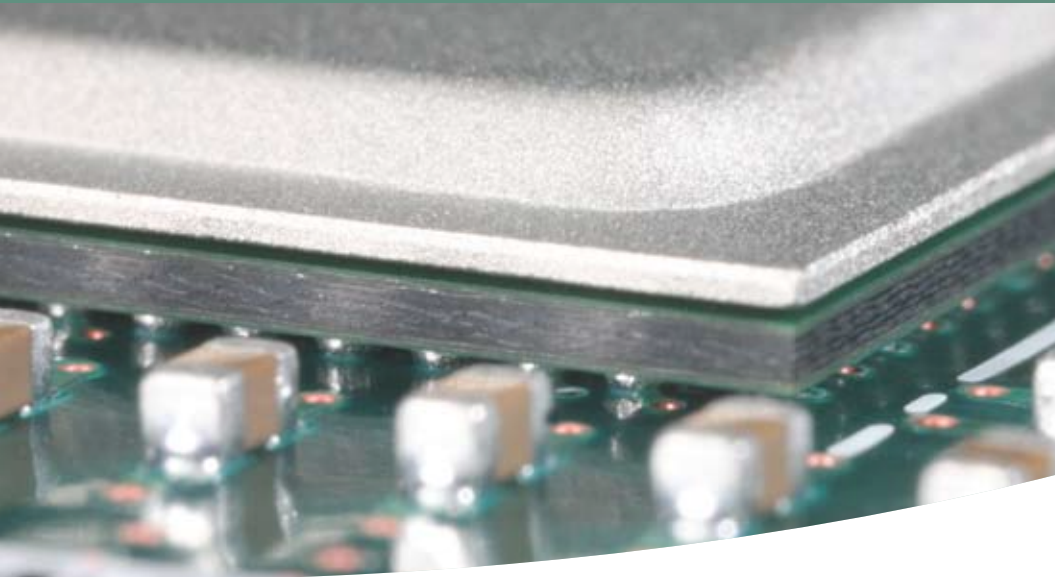


Complex Assembly Solutions



Assembly Solutions Expertise

EI merges engineering, manufacturing, product reliability and life cycle support expertise into assembly solutions that not only exceed your expectations, but also surpass industry standards. The power of our solutions lie in the ability to provide you with a breadth of products and services all under one roof. We can build your prototypes, design a process to address a new technology, handle your assembly challenges, and then develop and execute in-circuit or functional tests. Through the broad depth of our knowledge and experience, we will help you reduce your product development time and boost your profitability during each product life cycle phase.

EI delivers a unique mix of leading edge technology and technical expertise that gives our customers a time-to-market advantage and competitive differentiation. Our solutions support the needs of the information technology, defense and aerospace, telecommunications, advanced test equipment and medical markets where highly reliable products built in robust manufacturing operations are essential to success.

Features

Production of a wide range of products from high-end, complex, mission critical assemblies to lower complexity, support PCB assemblies

Full hybrid assembly, backplane, chassis and system build

Focused NPI to production launch of products with dedicated program managers and engineering support

Outstanding service and on-time delivery performance that consistently rates 99% or better

Extensive quality and process controls integrated within all our business processes, including:

Traceability system tracks/documents components and materials throughout each product's manufacture

Comprehensive process capabilities such as stencil design, automated solder inspection, AOI/X-ray examination, cleaning, rework/repair methods and high reliability testing

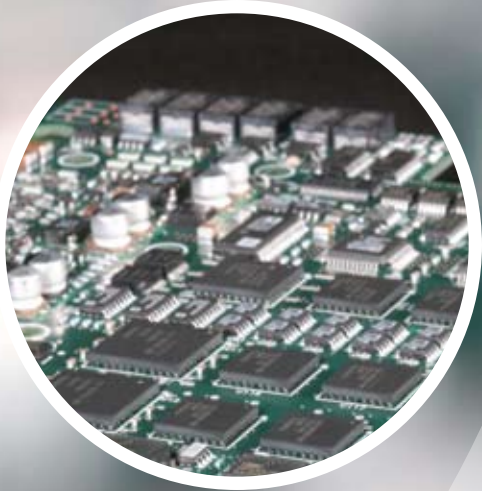
Extensive test development and execution capabilities including FHP, ICT, and FCT using both industry accepted and EI developed protocols, methods and equipment

Leading edge assembly process development including RoHS conversion and optimization

Flexible, competitive supply chain management capabilities integrated into our execution model

Outstanding life cycle support includes analysis, repair and upgrade, testing and more

Complex Assembly Solutions



Capabilities

Maximum Assembly Size

38" x 36" for SMT
36" x 48" for non-SMT backplanes
0.350" thickness

Technology

SMT
Press fit
Wave solder and selective PTH solder
Hand assembly and solder
LGA

Components

BGA/CGA down to 1.0mm pitch
 μ BGA and CSP down to 0.5mm pitch
DCA wire bond and flip chip
Perimeter lead fine pitch to 10 mils
LGA pitch down to 1.0mm
SMT discretes and chips down to 0201

Core Product Parametrics

Very thick PCBs; high density hybrid assemblies (average components >1500); double-sided, large, complex boards with mixed technology
Hybrid assemblies (SMT/PTH/press fit)
Components: high I/O area array modules (CGA, LGA, PBGA)
Connectors: dense, high I/O connectors
Mechanical: cage, chassis, system assemblies
High density BGA/area array rework

Testing

Genrad 2286, 2287, 2287LX, 2287LX Ultraprobe
Scorpion Flying Probe
Functional system level
ESS and burn-in

Certifications

ISO 9001: 2000
ISO 14001: 1996
IPC-A-610

For more detailed information about our complex assembly solutions, call us today at 866-820-4820. Our application engineers are ready to assist you with detailed information for successful design and build. You can also visit our website at www.endicottinterconnect.com.



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For more information, visit our website at www.endicottinterconnect.com